OUR PARTNERS

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Aptiv’s Smart Vehicle Architecture™ is an optimized and sustainable architecture that enables feature rich, highly automated vehicles. These solutions are increasingly delivered through software, which requires more flexible and scalable platforms to run on, supported by faster, more reliable high-speed connectivity and data networks. Valens’ automotive chipset is embedded in Aptiv’s PowerData Center (PDC) device for high performance in-vehicle data transmission.

"Aptiv has been working closely with Valens on our Smart Vehicle Architecture™. SVA™ shows the clear advantages of a centralized approach to high speed connectivity. Aptiv’s ring topology and high performance computing based on PCIe transmitted over Valens’ technology delivers the right balance of flexibility, performance and reliability as we continue down the path of supporting these feature rich highly automated vehicles."

Lee Bauer, Vice President, Mobility Architecture Group, Aptiv
AVNET is revolutionizing the market with ADAS reference designs, leveraging multi-function sensor technology to monitor lane drift and for collision avoidance. Avnet is partnering with Valens to leverage long-distance automotive PCIe connectivity.

We are working closely with Valens to support video/sensor fusion and ADAS platforms by connecting two of Avnet’s S32V platforms with Valens’ VA608A chipsets, optimizing in-vehicle connectivity.”
Matthew Wa, Avnet
Brose is a leading manufacturer of mechatronic systems for vehicle doors and seats as well as electric motors, drives and electronics. With Valens Automotive, Brose is able to considerably simplify door connectivity, by converging several interfaces over the same wire, and substantially reduce the number of wires.

Valens Automotive technology can replace 20+ cables with a one single unshielded twisted pair (UTP) wire, for easier installation and maintenance, and lower overall costs.”

Thomas Weingärtner, Brose
CSI-Online, a leading automotive design house in Germany, has partnered with Valens to develop an advanced multi-sensor door concept, addressing the challenges of in-vehicle door connectivity.

“The ability to converge different interfaces over the same wiring brings considerable benefits to door connectivity. By implementing Valens’ chipsets in our multi-sensor door concept, we can offer a more flexible and cost-effective architecture, while delivering high bandwidth and low latency.”

CSI-Online
At the forefront of in-vehicle connectivity today, Daimler has selected Valens Automotive as the technology of choice to guarantee high performance of advanced infotainment, ADAS, and telematics systems.

“One of Daimler’s strategic focus is to be a technological leader – in ‘green’ technologies, safety, autonomous driving and connectivity. Valens Automotive is a perfect fit as its architectural benefits, reliability and robustness lead to a superior driving experience to our customers.”

Daimler
As a leading global manufacturer of automotive parts, DENSO is collaborating with Valens to develop an advanced physical architecture, that enables redundant high-speed connectivity among area control units (ACU), endpoint ECUs and sensors/actuators, and additional plug-and-play equipment installation.

“Redundancy is an important element in the connectivity among different area control units (ACUs) and each to a centralized computer unit, guaranteeing error-free data transmission.”

DENSO
Geely Auto Group is a leading automobile manufacturer based in Hangzhou, China, focused on developing the most advanced and safest connected cars, and is partnering with Valens to optimize in-vehicle connectivity.

“As we look forward towards the autonomous car, we must count on the most reliable in-vehicle connectivity technology. Valens brings the necessary performance and resilience for the market to go forward.”

Geely
HARMAN designs and engineers connected products and solutions for the automotive market as well as other sectors. HARMAN has been working closely with Valens to guarantee high-speed head unit and rear seat unit (RSU) connectivity.
Leopard Imaging is a leader in high-definition embedded camera technologies and is revolutionizing the automotive sector with its superior performance. Leopard is working closely with Valens to build an optimized system-level support for the MIPI® Alliance’s A-PHY standard.

“High-definition imaging is a critical element to guarantee safety in connected and autonomous vehicles. Our partnership with Valens combines our superior software technology and Valens’ resilient infrastructure to guarantee ultra-high-speed data transmission from sensors and cameras to the ECUs in the car.”

Bill Pu, Co-Founder & President at Leopard Imaging
LG Innotek develops key materials and components for several sectors, including automotive. LG Innotek is developing its UHS C-Module – Ultra High Speed Communication – with Valens’ technology.

“LG Innotek is developing an advanced module for optimized TCU connectivity, thanks to Valens’ long-reach automotive PCIe connectivity, which enables ultra-high speed, convergence of different modems, and high resilience to EMI.”
Next-generation automotive architectures are readily adopting the technologies and capabilities that can be found in today’s enterprise applications. Remotely located centralized storage solutions offering high performance, high availability and high data integrity reflect an important architectural shift from historical distributed storage solutions. High-speed, cost-effective, robust and EMI-friendly connectivity solutions such as Valens’ proven technology are of paramount value in realizing practical implementations of centralized storage solutions in the automobile.

“As a leading innovator of memory and storage technologies, Micron has several decades of experience working with automotive and industrial manufacturers to address their challenges. “The Micron 2100 SSD offers industry-leading capacity, performance, reliability and low-cost storage in a small form factor.”

Aravind Ramamoorthy, NAND product line senior director for Micron’s Embedded Business Unit
mk-messtechnik GmbH is a world leader in the field of optical test and measuring systems for EMC testing.

"Valens is our partner in development of our brand new device optoHDBaseT based on Valens VA6000 chip."
OmniVision is a leading developer of advanced digital imaging solutions targeting automotive applications, among others. OmniVision and Valens are partnering to advance fail-safe, highly resilient solutions for long-reach, native CSI-2 transmission, based on the MIPI® Alliance A-PHY standard.

“Vision systems are at the heart of ADAS platforms. By working with Valens, we can implement standard-compliant, long-reach native CSI-2 transmission over a simple infrastructure.”

Andy Hanvey, Director, Automotive Marketing, OmniVision
ON Semiconductor is the #1 supplier of CMOS image sensors for viewing and Automated Driver Assistance Systems (ADAS). ON Semiconductor & Valens are partnering to enable ultra-high-speed long-reach CSI-2 transmission based on the MIPI® Alliance A-PHY standard.

“As a member of the MIPI Alliance, ON Semi is engaged in advancing ultra-high-speed transmission in the connected car. As the baseline of the A-PHY standard, Valens’ technology is a key element in our efforts towards addressing the demands of the automotive sector.”

ON Semiconductor
Qualcomm Technologies is a leader in the wireless sector, with modular solutions that help carmakers integrate cutting-edge wireless and compute technologies into today’s connected cars. Qualcomm Technologies has been partnering with Valens to address the challenges of 5G connectivity and in-vehicle transmission in the connected car.

“5G and multiGig wireless connectivity are important elements of the evolution of connected cars, offering enhanced in-vehicle and V2X communications. Valens’ automotive technology enables ultra-high bandwidth, next-generation applications and in-car experiences based on 5G and wireless connectivity by extending PCIe interfaces and simplifying in-vehicle architecture.”

Matthew Eichenberger, Qualcomm
Rosenberger is a leading manufacturer of connectivity solutions, with a wide range of standardized and customized components in the automotive sector. Valens and Rosenberger are working together with the H-MTD® (High-speed Modular Twisted Pair Data automotive connector system), which enables high-bitrate data transmission while saving installation space and weight, with increased modularity and flexibility to address a range of applications.

“As a company committed to connectivity, our joint projects with Valens bring considerable benefits to the automotive sector, providing a superior solution for enhanced communication, safety and performance for the connected car.”

Gregor Reiner, VP of BA Automotive, Rosenberger
With a diverse portfolio of advanced automotive components, Samsung’s industry-leading semiconductors offer a reliable foundation for the future of mobility, bringing in-vehicle infotainment and ADAS to a new level. As a long-time partner and investor of Valens, the companies are now collaborating on innovative automotive technology projects, advancing in-vehicle connectivity.
A world leader in the semiconductor market, STMicroelectronics is partnering with Valens to develop synchronized Distributed Remote Tuner Concepts. It allows flexible and simplified module design, eliminating unnecessary devices and addressing the demand for Software Defined Radio benefitting from the high bandwidth of the Valens interface ICs.

“Over the past three years, ST has worked with Valens in several projects to advance ultra-high-speed in-vehicle connectivity, bringing considerable benefits to OEMs and Tier-1s.”

ST
Automobiles are using TE’s advanced technology to enhance communication, safety, and performance – within the car, between vehicles, and to other devices and machines. TE connectivity solutions are utilized with Valens’ technology and are part of Valens’ first automotive design win.

“As a company committed to connectivity, our joint project with Valens brings considerable benefits to the automotive sector, providing a superior solution for enhanced communication, safety and performance for the connected car.”

TE Connectivity
Tektronix designs and manufactures test and measurement solutions for a range of sectors, including mobility. Tektronix has adapted their test and measurement equipment to support transmitter tests as part of Automotive Compliance Tests.

“As a company committed to performance, our joint project with Valens brings considerable benefits to the automotive sector, providing a superior solution for increased safety and security for the connected car.”

Tektronix
TSN provides high-level tools for test & measurement of automotive connectivity links, with a highly intuitive user interface. TSN tools covers Valens’ technology transmission, guaranteeing superior performance.

“Reliable connectivity demands thorough test and measurement equipment, particularly for high bandwidth and time sensitive signals. Our TSN Box incorporates Valens’ technology for any automotive installation, providing nanosecond-level precision in its capabilities.”

Jürgen Scheuring, Managing Director, TSN Systems
TTTech Auto designs and implements safety-critical and future-proof platform-centric solutions. TTTech Auto has incorporated Valens’ chipsets in its revolutionary In-Car Compute Platform, consolidating a range of functions from different domains inside a single, high performance ECU.

“With its high-speed network technology, Valens contributed to TTTech Auto’s development of an advanced In-Car Compute Platform, delivering highest safety through fail-operational capabilities, achieving high flexibility through a scalable solution, and simple software integration with an open and modular platform.”

Georg Kopetz, CEO, TTTech Auto